

METHOD AND SYSTEM FOR INTEGRATED CIRCUIT BONDING

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ABSTRACT OF THE DISCLOSURE

According to one embodiment of the invention, a method for adhering an integrated circuit to a substrate includes receiving a boat configured to hold a plurality of substrates at a first position. The substrates include a first surface configured to support an integrated circuit. The boat of substrates is heated at the first position. The boat of substrates is transferred from the first position to a second position. The integrated circuit is positioned on the first surface of a selected one of the plurality of substrates at the second position. The integrated circuit includes an adhesive surface operable to adhere the integrated circuit to the selected substrate.

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